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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Rich Fogal and Michael B. Ball

Serial No.: 09/422,887

Filed: October 21, 1999

For: ANGULARLY OFFSET STACKED DIE MULTICHIP  
DEVICE AND METHOD OF MANUFACTURE

§  
§ Group Art Unit: 2822  
§  
§ Examiner: J. Brophy  
§  
§ Atty. Docket: 95-0134.05  
§  
§  
§  
§

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1C 2800 MAIL ROOM

FORMAL DRAWINGS TRANSMITTAL

Attn: Office of Official Draftsperson/Drawing Review Branch

Commissioner for Patents

Washington, D.C. 20231

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I hereby certify that this correspondence is being deposited  
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2/19/02 Susan Ferguson  
Date Signature

Dear Sir:

Applicants herein submit substitute formal drawings in triplicate in addition to a redlined  
copy. A copy of these drawings have been sent to the Examiner.

Approved  
Q.B.  
6/18/02

2/19/02

Respectfully submitted,

Charles Brantley

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